

			PMP8493 REVB BOM			11/2/2012
COUNT	RefDes	Value	Description	Size	Part Number	Mfr
3	C7, C12, C15	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	C5, C103	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C9	1800pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C8	18pF	Capacitor, Ceramic, 50V, NPO, 10%	0603	Std	Std
1	C13	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
1	C16	680pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
3	C1, C14, C102	4.7uF	Capacitor, Ceramic, 25V, X7R, 15%	0805	C2012X7R1E475MT	TDK
2	C2, C3	22uF	Capacitor, 25V, 0.045 ohms, 1.5A	7343(D)	25TQC22MV	Sanyo
2	C100, C101	47uF	Capacitor, 16V, 0.040 ohms, 1.8A	7343(D)	16TQC47MW	Sanyo
1	L1	6.8uH	Inductor, 8A, 21.2 milliohms	10.3x11.2mm	IHLP4040DZER6R8M01	Vishay
2	Q1, Q2	CSD18504Q5A	MOSFET, Nch, 40V, 5.3 milliohm	SON5X6	CSD18504Q5A	TI
3	R7, R100, R101	4.7	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
2	R1, R2	499K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R10	18.2K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R13	23.2K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R14	8.06K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R15	2.10K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R17	49.9	Resistor, Chip, 1%, 0603	0603	Std	Std
1	R18	2.74K	Resistor, Chip, 1%, 0603	0603	Std	Std
1	R3	28K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
2	R4, R16	49.9K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R5	0	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
2	R9, R12	10K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R102	2.7	Resistor, Chip, 1/4-W, 1%	1206	Std	Std
1	U1	TPS40170RGY	IC, 4.5V-60V Wide Input Sync Buck Controller	QFN-20	TPS40170RGY	TI
MISC						
1	J2	B3P-VH	Connector, Top 3-pin, 156 mil spacing,	0.465 X 0.335 inch	B3P-VH	JST
1	J3	B2P-VH	Connector, Top Entry 2-pin, 156 mil spacing,	0.465 X 0.370 inch	B2P-VH	JST
6	TP2, TP6, TP7, TP8, TP11, TP12	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
3	TP3, TP9, TP10	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone

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